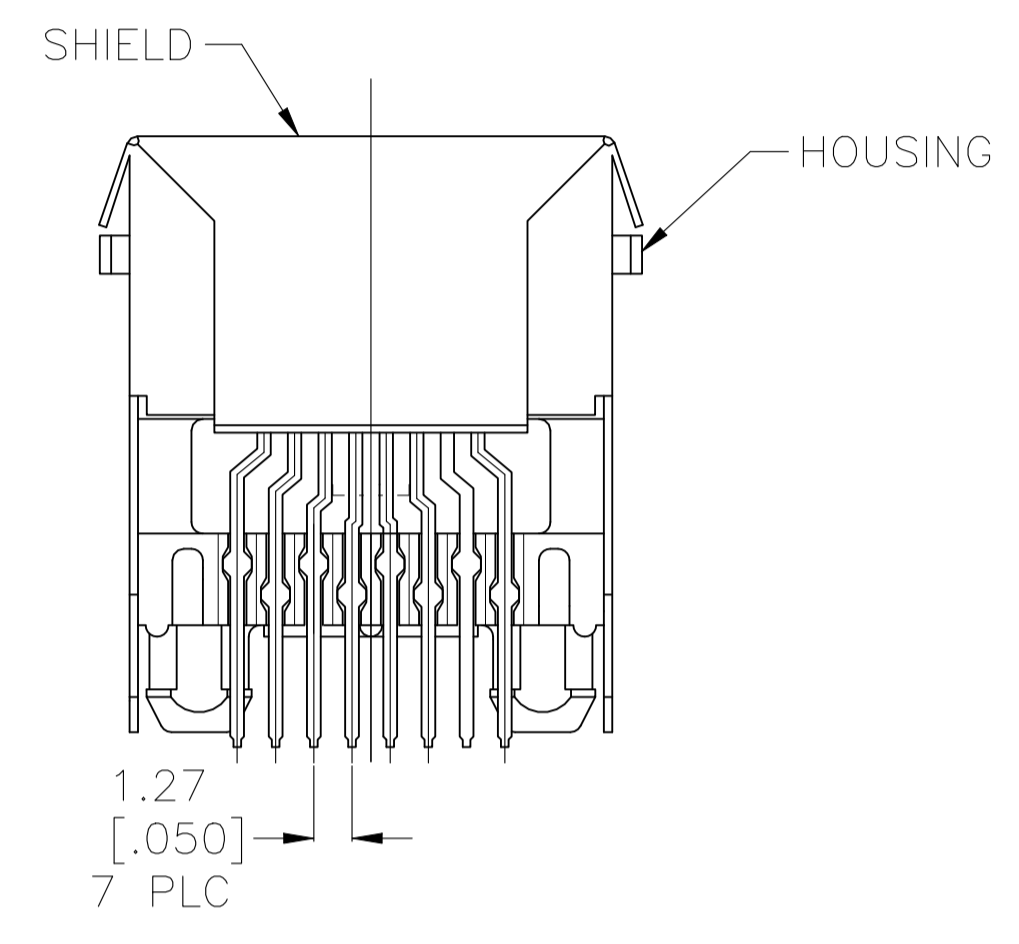
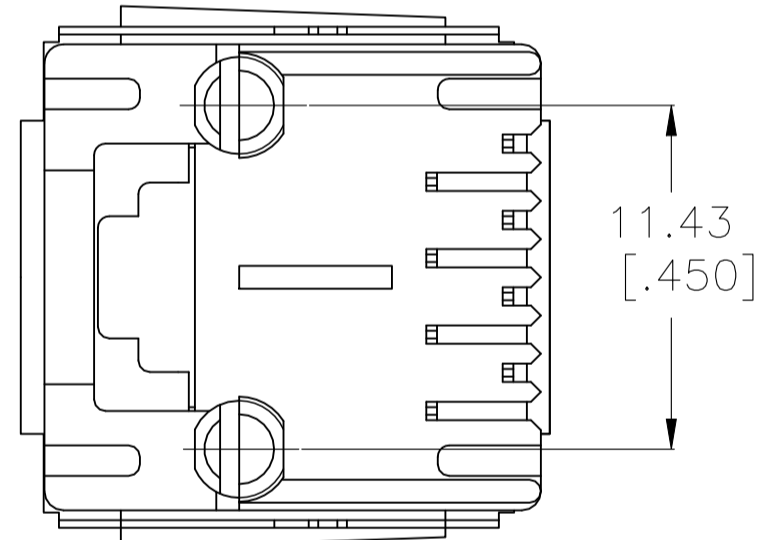
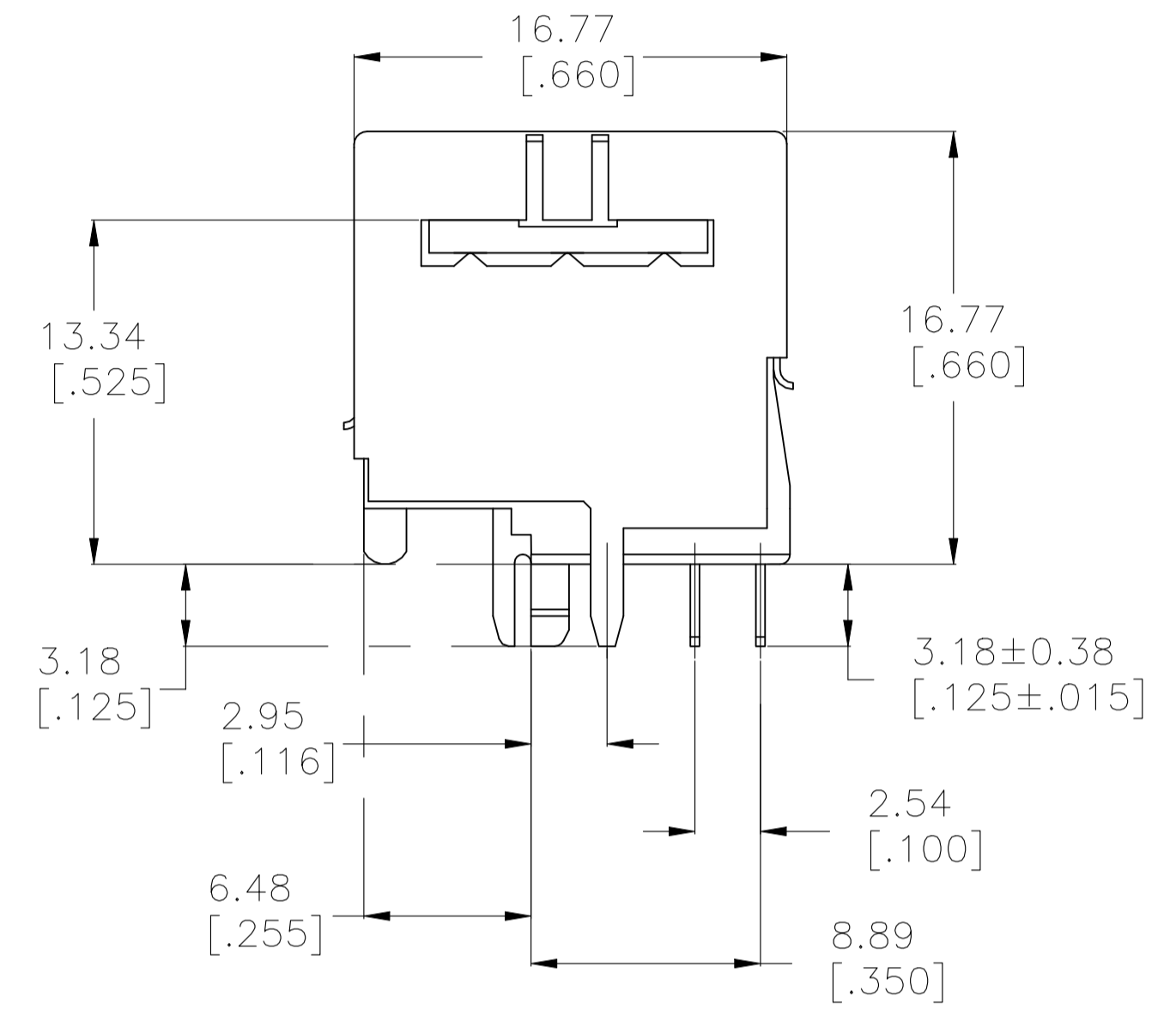
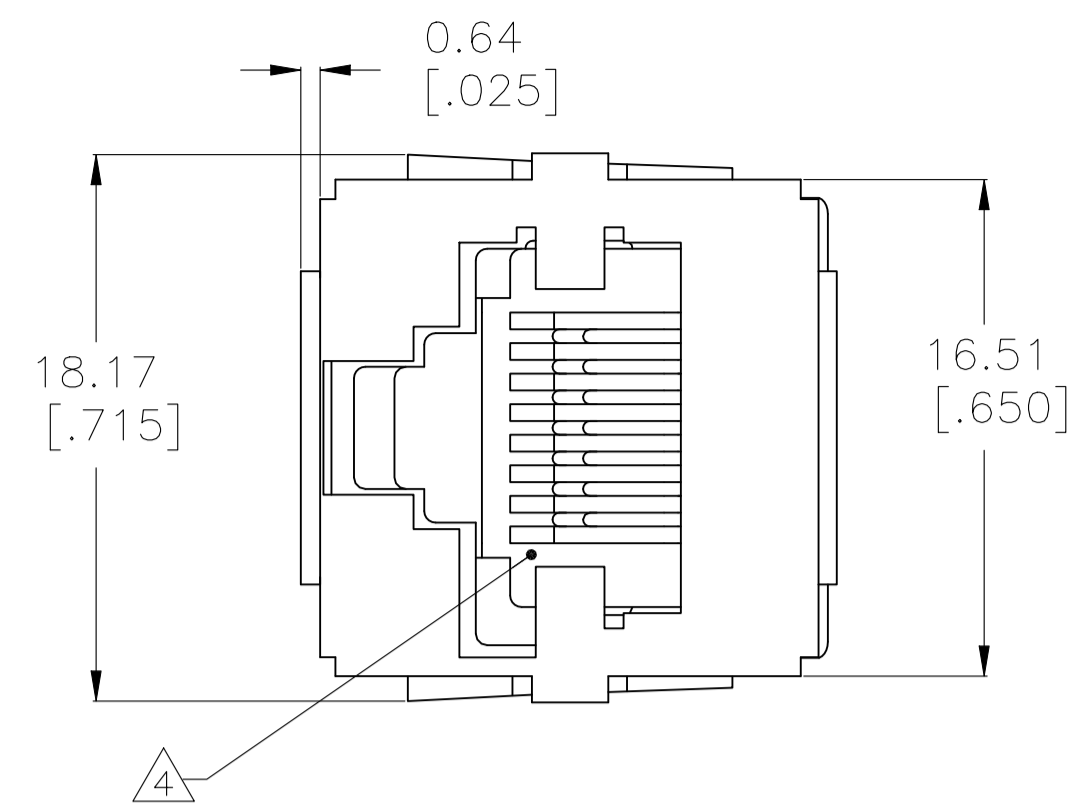
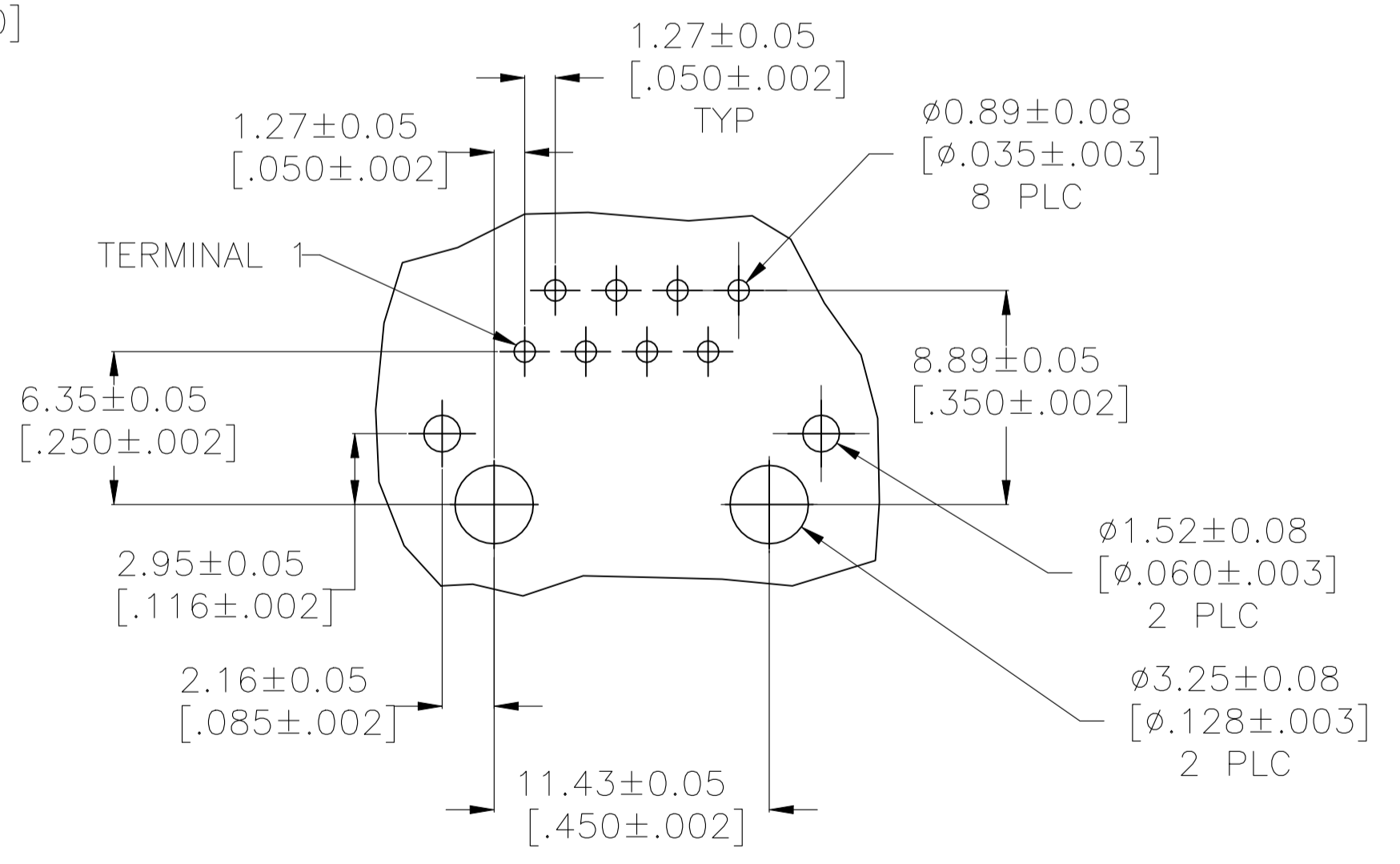


REVISIONS					
REV	DESCRIPTION	DATE	BY	CHK	APP'D
C2	REVISED AS PER ECN-24-255043	06MAR2024	JK	WH	

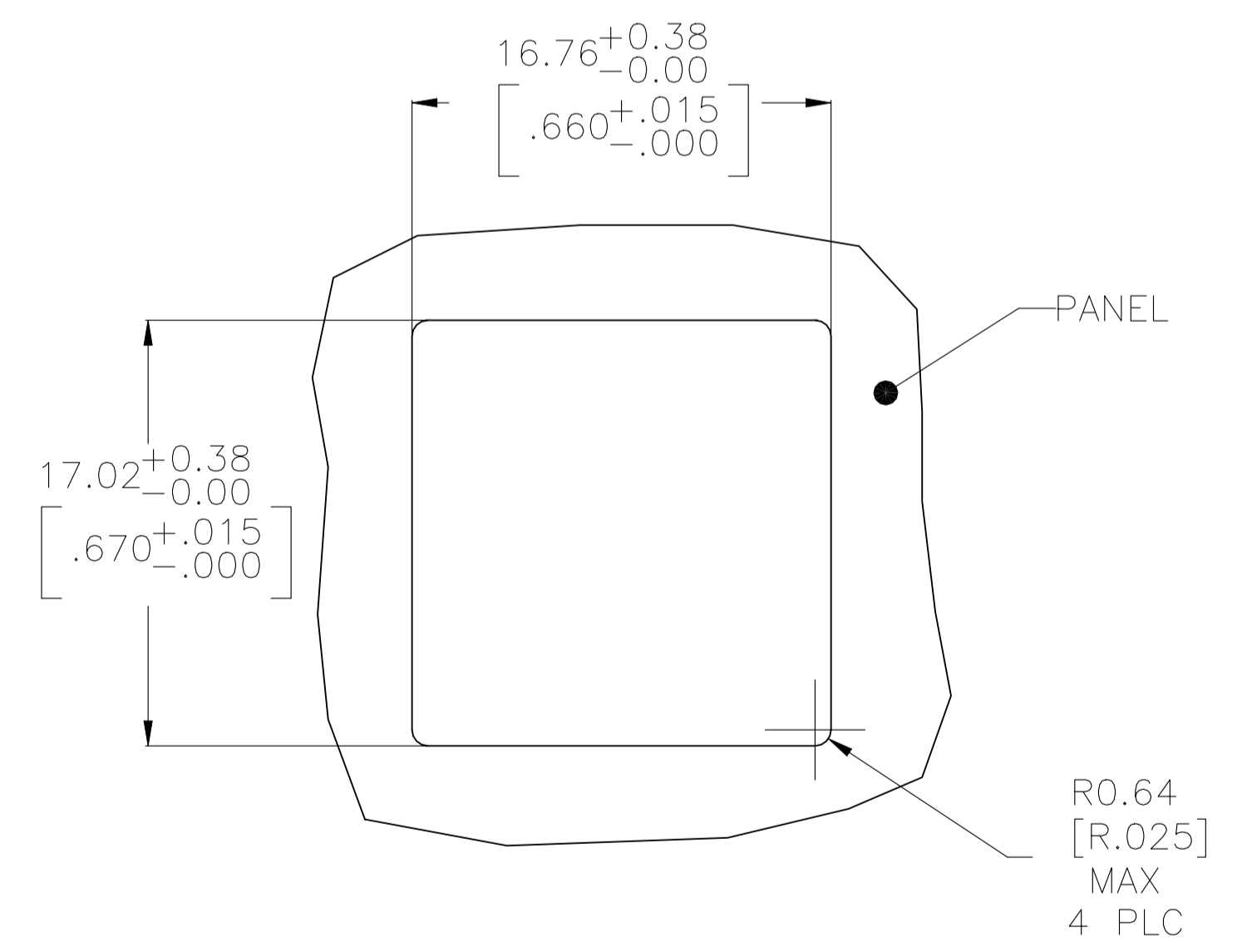


1. MATERIAL:
 HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
 TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27 μ m[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81 μ m[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MIN THICK NICKEL UNDERPLATE
 SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0 μ m[.000120] MIN THICK REFLOWED TIN.

2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

5557730-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN D. STRAUSSER/22APR2005		J.WESTMAN/22APR2005		S.FLICKINGER/22APR2005		NAME		MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		0 PLC ± -		1 PLC ± -		2 PLC ± 0.13[.005]		3 PLC ± -	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT 0.000000		A1 00779		C=5557730		CUSTOMER DRAWING	
				SCALE 4:1		SHEET 1 of 1		REV C2			